

Material Data Sheet

MKD AC Film Capacitor

Product Class	B32370* and series	FilterCap MKD AC: B32370* and B32375* series November 1st, 2019								
Date	November 1 st , 2			1						
IMDS ID if available				And and a second s	J					
Version 03				B32370		B32375				
Product Part (IMDS: semi component)	Material Class (IMDS: Material)	Materia (Classificat VDA 231		ince	TMPS**) [wt%]	CAS if applicable	Typical mass of material [wt-%]	Traces see 1)		
Active Part	Polymer	Polymer 2A		Polypropylene		9003-07-0	36.51			
	Light Metal	ight Metal 1B		AI		7429-90-5	0.20			
	Heavy Metal	1C	Zn		98	7440-66-6	13.24			
			others*):	2					
Encapsulation	Polymer	mer 2A		PP		9003-07-0	10.53			
Termination	Polymer	Polymer 2A		PBT		26062-94-2	6.82			
	Paper, Cardboard	,		Cellulose		9004-34-6	2.40			
	Polymer	2C	Polvure	Polyurethane resin		9003-29-6	11.62			
	Light Metal	1B		Al		7429-90-5	14.24			
	Metal	1A		Steel		7439-89-6	1.6			
	Metal	1C	Brass			7440-31-5	0.3			
	Metal	1C 1C		Sn		7440-31-5				
							0.93			
	Metal	1C		Copper		7440-50-8	0.9			
	Metal	1C	Ni		100	7440-02-0	0.02			
						Sum in total:	100			
sizes DxH[mm] 50x64~63.5x137				Part numbers: B32370X, B32375X						
Not Part of a Produc	ct Class									
Contact	Dennis Huang	Important remarks:								
Division	TDK (Zhuhai FTZ) Co., L	DK (Zhuhai FTZ) Co., Ltd			1) The declaration limit is 0.1% as defined by IEC 62474 (IEC PAS 61906). Traces are					
Address	City PR CHINA	b.4 Lianfeng Road, Xiangzhou District, 519030 Zhuhai ty PR CHINA mailto: <u>dennis.huang@tdk-electronics.tdk.com</u>				 product parts, substances etc. that are below a percentage of 0.1 % by weight, if not otherwise regulated. 2) This Material Data Sheet contains typical values of the respective products set forth herein. We expressly point out that all values and statements contained herein are 				
*) others: .(not declar	based on our best present knowledge and cannot be regarded as binding statements or binding product specifications, unless otherwise explicitly agreed in writing. TDK ELECTRONICS AG AND ITS AFFILIATES HEREBY EXPRESSLY DISCOLAIM ANY REPRESENTATION OR WARRANTY, WHETHER EXPRESS, IMPLIED OR STATUTORY, WITH REGARD TO THE STATEMENTS AND VALUES CONTAINED HEREIN, INCLUDING BUT NOT LIMITED TO ANY REPRESENTATION OR WARRANTY OF MERCHANTABILITY OR SUITABILITY FOR ANY PURPOSE.									
**) typical mass perce										
Directive 2011/65/EU of	rth herein are "RoHS-cor the European Parliament and for the Broduct Close (B	of the Council of June	e 8 th , 2011 on the re	striction of the use	of certain hazard					
☑ no exemptions;	for the Product Class / P		· ·							
	as an alloying element in aluminun		lead by weight;							
	per alloy containing up to 4 % lead b		nuo containin - OF 0/ Louis	unight or more lac -1						
	I in high melting temperature type so trical and electronic components co					ectronic devices or in a gla	ass or ceramic matrix compou	nd:		
	in dielectric ceramic in capacitors f									
	in dielectric ceramic in capacitors f	-		-						
Exemption 15: Lead	in solders to complete a viable elec	trical connection betwee	en semiconductor die an	d carrier within integr	rated circuit Flip Chip	packages;				
□ Other Exemption than ab	ove									